

X2-Class **Power MOSFET**

IXTA12N70X2 IXTP12N70X2 **IXTH12N70X2**

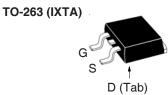
N-Channel Enhancement Mode

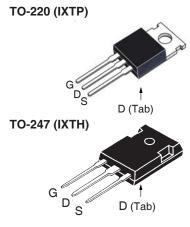


Symbol	Test Conditions	Maximum	Ratings
V _{DSS}	$T_J = 25^{\circ}C \text{ to } 150^{\circ}C$	700	V
V _{DGR}	$T_{_{\rm J}}$ = 25°C to 150°C, $R_{_{\rm GS}}$ = 1M Ω	700	V
V _{GSS}	Continuous	±30	V
V _{GSM}	Transient	±40	V
I _{D25}	T _c = 25°C	12	A
I _{DM}	$T_{c} = 25^{\circ}C$, Pulse Width Limited by T_{JM}	24	Α
I _A	$T_{c} = 25^{\circ}C$	6	Α
E _{AS}	$T_{c} = 25^{\circ}C$	300	mJ
dv/dt	$I_{_{\mathrm{S}}} \leq I_{_{\mathrm{DM}}}, V_{_{\mathrm{DD}}} \leq V_{_{\mathrm{DSS}}}, T_{_{\mathrm{J}}} \leq 150^{\circ}\mathrm{C}$	50	V/ns
P _D	T _c = 25°C	180	W
T _J		-55 +150	°C
T _{JM}		150	°C
T _{stg}		-55 +150	°C
T _L	Maximum Lead Temperature for Soldering	g 300	°C
T _{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
F _c M _d	Mounting Force (TO-263) Mounting Torque (TO-220 & TO-247)	1065 / 2.214.6 1.13 / 10	N/lb Nm/lb.in
Weight	TO-263	2.5	g
	TO-220 TO-247	3.0 6.0	g g

SymbolTest ConditionsCharacter $(T_J = 25^{\circ}C, Unless Otherwise Specified)$ Min.		cteristic Values Typ.			
BV _{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	700			V
$V_{\rm GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	2.5		4.5	V
I _{GSS}	$V_{gs} = \pm 30V, V_{DS} = 0V$			±100	nA
I _{DSS}	$V_{DS} = V_{DSS}$, $V_{GS} = 0V$ $T_{J} = 125$ °C				μ Α μ Α
R _{DS(on)}	$V_{GS} = 10V, I_{D} = 0.5 \bullet I_{D25}, Note 1$			300	mΩ

700V **12A** $300 m\Omega$





G = Gate	D	= Drain
S = Source	Tab	= Drain

Features

- International Standard Packages
- Low $R_{DS(ON)}$ and Q_G Avalanche Rated
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode **Power Supplies**
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls

SymbolTest ConditionsCha $(T_J = 25^{\circ}C, Unless Otherwise Specified)$ Min.			racteristic Values Typ. Max			
g _{fs}	V _{DS} = 10V, I _D = 0.5 • I _{D25} , Note 1	7	12	S		
R_{Gi}	Gate Input Resistance		3.7	Ω		
C _{iss}			960	pF		
C _{oss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		920	pF		
C _{rss}			2	pF		
	Effective Output Capacitance					
$C_{o(er)}$	Energy related $\int V_{GS} = 0V$		58	pF		
$C_{o(tr)}$	Time related $\int V_{DS}^{GS} = 0.8 \cdot V_{DSS}$		200	pF		
t _{d(on)}	Resistive Switching Times		24	ns		
t, ($V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25}$		30	ns		
t _{d(off)}	$R_{G} = 30\Omega$ (External)		78	ns		
t _f	Ti _G = 3032 (External)		27	ns		
Q _{g(on)}			19	nC		
Q _{gs}	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25}$		5	nC		
Q _{gd}			8	nC		
R _{thJC}				0.69 °C/W		
R _{thCS}	TO-220 TO-247		0.50 0.25	°C/W		

Source-Drain Diode

•			acteristic Values		
$(T_J = 25^{\circ}C, l)$	Jnless Otherwise Specified)	Min.	Тур.	Max	
Is	$V_{GS} = 0V$			12	Α
SM	Repetitive, pulse Width Limited by $T_{_{JM}}$			48	Α
V _{SD}	$I_F = I_S$, $V_{GS} = 0V$, Note 1			1.4	V
$\left. egin{array}{ll} oldsymbol{t_{rr}} & & \ oldsymbol{Q_{RM}} & \ oldsymbol{I_{RM}} & \end{array} ight. ight.$	$I_F = 6A, -di/dt = 100A/\mu s$ $V_R = 100V$		270 2.8 21		ns µC A

Note 1. Pulse test, $t \le 300\mu s$, duty cycle, $d \le 2\%$.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

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Fig. 1. Output Characteristics @ $T_J = 25$ °C

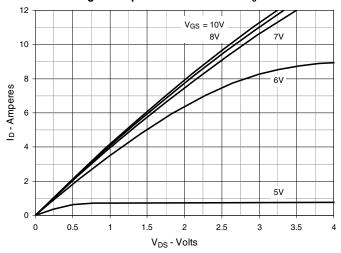


Fig. 2. Extended Output Characteristics @ T_J = 25°C

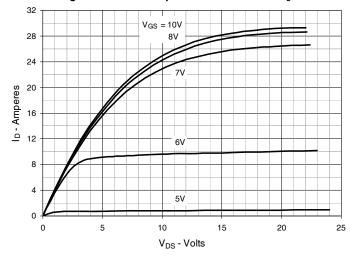


Fig. 3. Output Characteristics @ T_J = 125°C

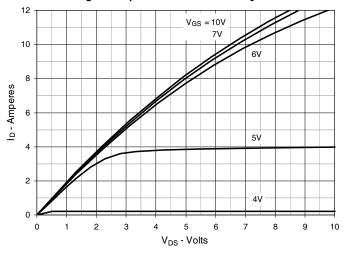


Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 6A$ Value vs. **Junction Temperature**

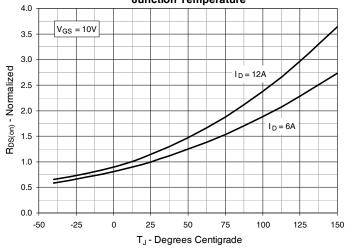


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 6A Value vs.

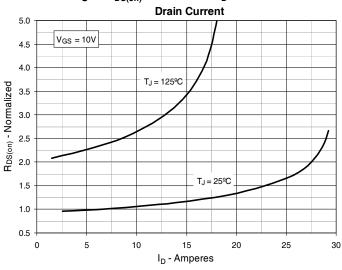


Fig. 6. Normalized Breakdown & Threshold Voltages

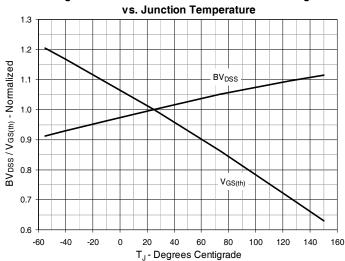




Fig. 7. Maximum Drain Current vs. Case Temperature

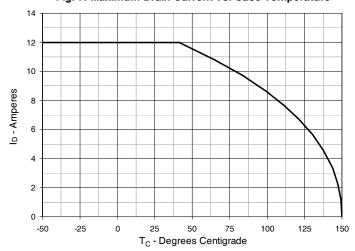


Fig. 8. Input Admittance

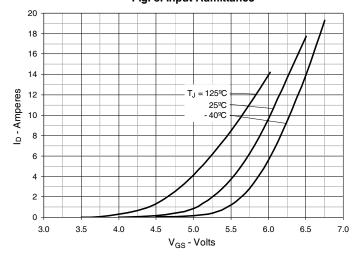


Fig. 9. Transconductance

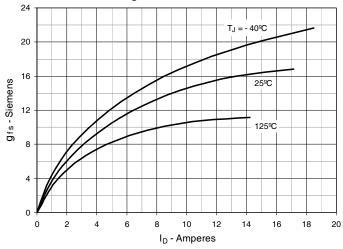


Fig. 10. Forward Voltage Drop of Intrinsic Diode

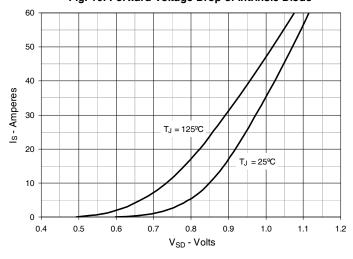


Fig. 11. Gate Charge

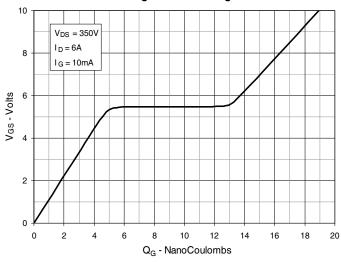
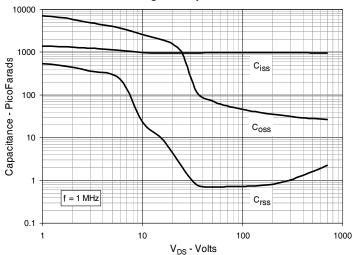
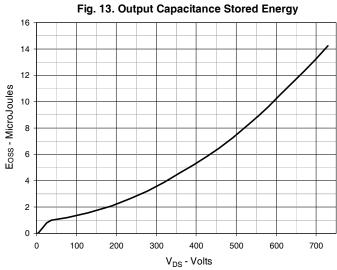


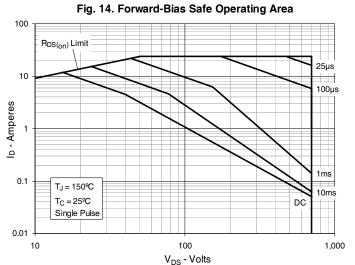
Fig. 12. Capacitance

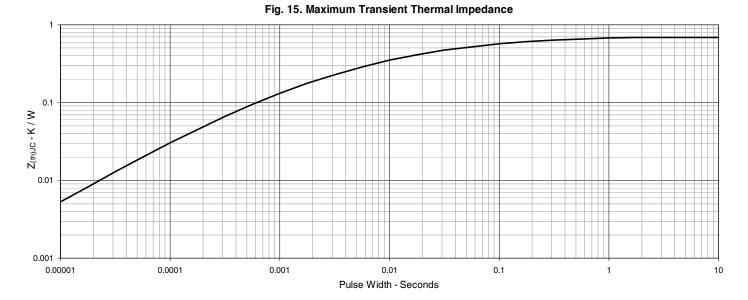


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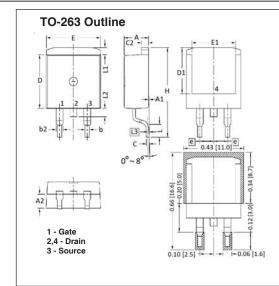




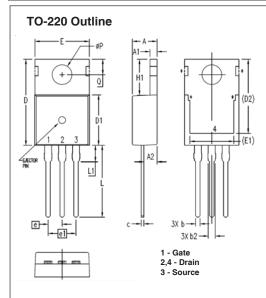




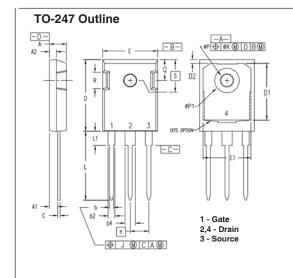




CVII	INCHES		MILLIMETER		
SYM	MIN	MAX	MIN	MAX	
Α	.170	.185	4.30	4.70	
A1	.000	.008	0.00	0.20	
A2	.091	.098	2.30	2.50	
Ь	.028	.035	0.70	0.90	
b2	.046	.060	1.18	1.52	
С	.018	.024	0.45	0.60	
C2	.049	.060	1.25	1.52	
D	.340	.370	8.63	9.40	
D1	.300	.327	7.62	8.30	
E	.380	.410	9.65	10.41	
E1	.270	.330	6.86	8.38	
е	.100	BSC	2.54 BSC		
Н	.580	.620	14.73	15.75	
L	.075	.105	1.91	2.67	
L1	.039	.060	1.00	1.52	
L2	_	.070	_	1.77	
L3	.010	BSC	0.254	BSC	



MYZ	INC	HES MILLI		ETERS
21M	MIN	MAX	MIN	MAX
Α	.169	.185	4.30	4.70
A1	.047	.055	1.20	1.40
A2	.079	.106	2.00	2.70
Ь	.024	.039	0.60	1.00
b2	.045	.057	1.15	1.45
O	.014	.026	0.35	0.65
D	.587	.626	14.90	15.90
D1	.335	.370	8.50	9.40
(D2)	.500	.531	12.70	13.50
Ε	.382	.406	9.70	10.30
(E1)	.283	.323	7.20	8.20
е	.100 BSC		2.54	BSC
e1	.200 BSC		5.08	BSC
H1	.244	.268	6.20	6.80
٦	.492	.547	12.50	13.90
L1	.110	.154	2.80	3.90
ØΡ	.134	.150	3.40	3.80
Q	.106	.126	2.70	3.20



SYM	INCHES		MILLIMETERS	
STIVI	MIN	MAX	MIN	MAX
Α	.190	.205	4.83	5.21
Α1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
Ь	.045	.055	1.14	1.40
b2	.075	.087	1.91	2.20
b4	.115	.126	2.92	3.20
С	.024	.031	0.61	0.80
Ď	.819	.840	20.80	21.34
D1	.650	.690	16.51	17.53
D2	.035	.050	0.89	1.27
E	.620	.635	15.75	16.13
E1	.545	.565	13.84	14.35
е	.215	BSC	5.45 BSC	
J		.010		0.25
K		.025		0.64
L	.780	.810	19.81	20.57
L1	.150	.170	3.81	4.32
ØΡ	.140	.144	3.55	3.65
øP1	.275	.290	6.99	7.37
Q	.220	.244	5.59	6.20
R	.170	.190	4.32	4.83
S	.242 BSC		6.15	BSC

